

ABSTRACT

Disclosed is a film-shaped adhesive for adhering a semiconductor element to a support member for mounting the semiconductor element. The film-shaped adhesive contains a heat-curable resin, a curing agent, an acrylic rubber, and a heterocyclic compound, and in the infrared absorption spectrum of the acrylic rubber, when the height of an absorption peak originating from stretching vibration of a carbonyl group is designated as P_{CO} , and the height of a peak originating from stretching vibration of a nitrile group is designated as P_{CN} , P_{CO} and P_{CN} satisfy the condition of the following Formula (1), and the thickness of the film-shaped adhesive is 50 μm or less:

$$P_{CN}/P_{CO} < 0.070 \quad (1).$$

Fig. 1